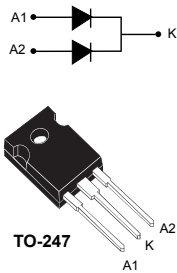


## 100 V power Schottky rectifier



### Features

- High junction temperature capability
- Low leakage current
- Good trade-off between leakage current and forward voltage drop
- Low thermal resistance
- High frequency operation
- ECOPACK<sup>®</sup>2 compliant

### Applications

- Switching diode
- SMPS
- DC/DC converter
- Telecom power
- Desktop power supply

### Description

This dual diode common cathode Schottky rectifier is suited for high frequency switched mode power supplies.

Packaged in TO-247, the **STPS61H100C** is optimized for use to enhance the reliability of the application.

Product status	
STPS61H100C	
Product summary	
$I_{F(AV)}$	2 x 30 A
$V_{RRM}$	100 V
$T_{j(max.)}$	175 °C
$V_{F(typ.)}$	0.63 V

# 1 Characteristics

**Table 1. Absolute ratings (limiting values per diode at 25 °C, unless otherwise specified)**

Symbol	Parameter	Value	Unit	
$V_{RRM}$	Repetitive peak reverse voltage	100	V	
$I_{F(RMS)}$	Forward rms current	80	A	
$I_{F(AV)}$	Average forward current, $\delta = 0.5$ , square wave	$T_c = 150\text{ °C}$ Per diode	30	A
		$T_c = 145\text{ °C}$ Per device	60	
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms}$ sinusoidal	450	A
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 10\text{ }\mu\text{s}$ , $T_j = 125\text{ °C}$	1900	W
$T_{stg}$	Storage temperature range	-65 to +175	°C	
$T_j$	Maximum operating junction temperature <sup>(1)</sup>	+175	°C	

1.  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

**Table 2. Thermal resistance parameters**

Symbol	Parameter	Max. value	Unit	
$R_{th(j-c)}$	Junction to case	Per diode	0.9	°C/W
		Total	0.6	
$R_{th(c)}$	Coupling	0.3	°C/W	

When the diodes 1 and 2 are used simultaneously:  $\Delta T_j(\text{diode1}) = P_{(\text{diode1})} \times R_{th(j-c)}$  (per diode) +  $P_{(\text{diode2})} \times R_{th(c)}$

For more information, please refer to the following application note :

- AN5088 : Rectifiers thermal management, handling and mounting recommendations

**Table 3. Static electrical characteristics (per diode)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit	
$I_R$ <sup>(1)</sup>	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-	3	16	$\mu\text{A}$
		$T_j = 125\text{ °C}$		-	4	16	mA
$V_F$ <sup>(2)</sup>	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 30\text{ A}$	-		0.79	V
		$T_j = 125\text{ °C}$		-	0.63	0.67	
		$T_j = 25\text{ °C}$	$I_F = 60\text{ A}$	-		0.93	
		$T_j = 125\text{ °C}$		-	0.72	0.78	

1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

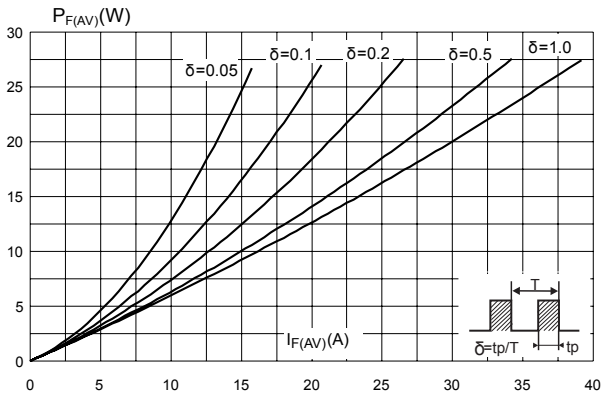
To evaluate the conduction losses, use the following equation:  $P = 0.56 \times I_{F(AV)} + 0.0036 \times I_F^2$  (RMS)

For more information, please refer to the following application notes related to the power losses :

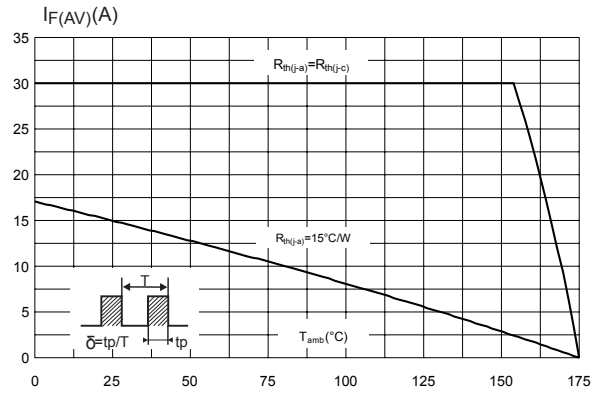
- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

### 1.1 Characteristics (curves)

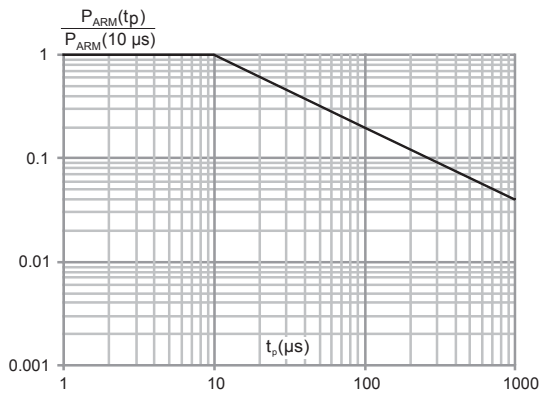
**Figure 1. Average forward power dissipation versus average forward current (per diode)**



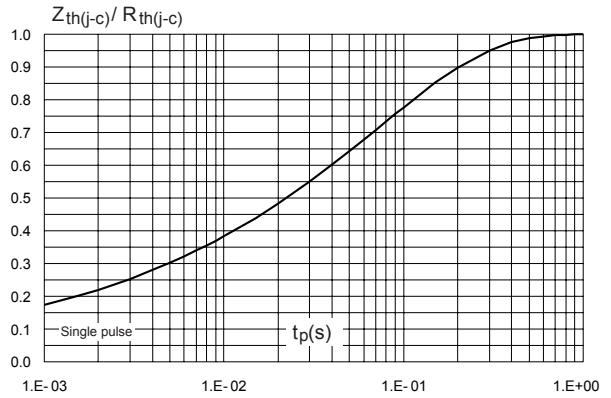
**Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ , per diode)**



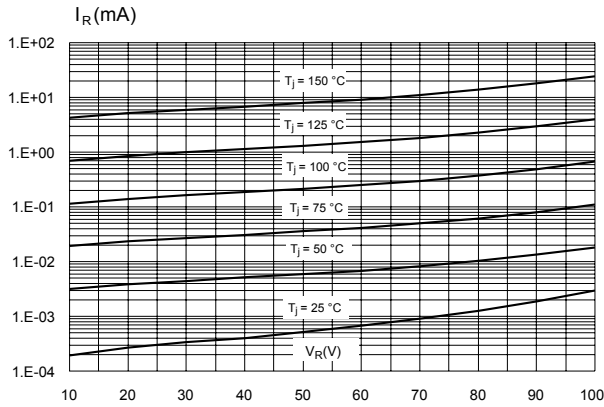
**Figure 3. Normalized avalanche power derating versus pulse duration ( $T_j = 125^\circ\text{C}$ )**



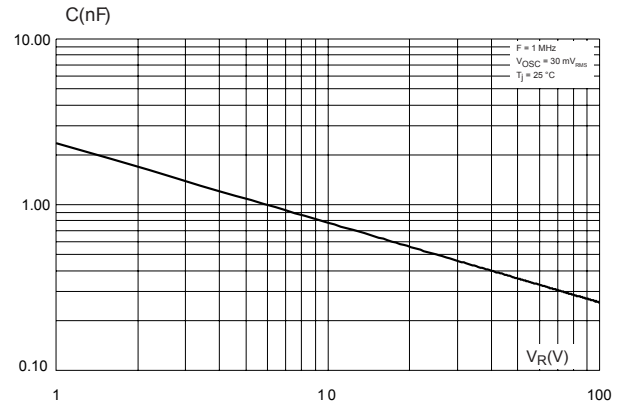
**Figure 4. Relative variation of thermal impedance junction to case versus pulse duration**



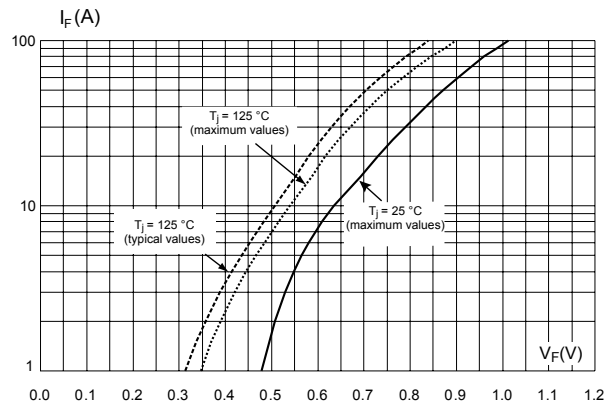
**Figure 5. Reverse leakage current versus reverse voltage applied (typical values, per diode)**



**Figure 6. Junction capacitance versus reverse voltage applied (typical values, per diode)**



**Figure 7. Forward voltage drop versus forward current (per diode)**



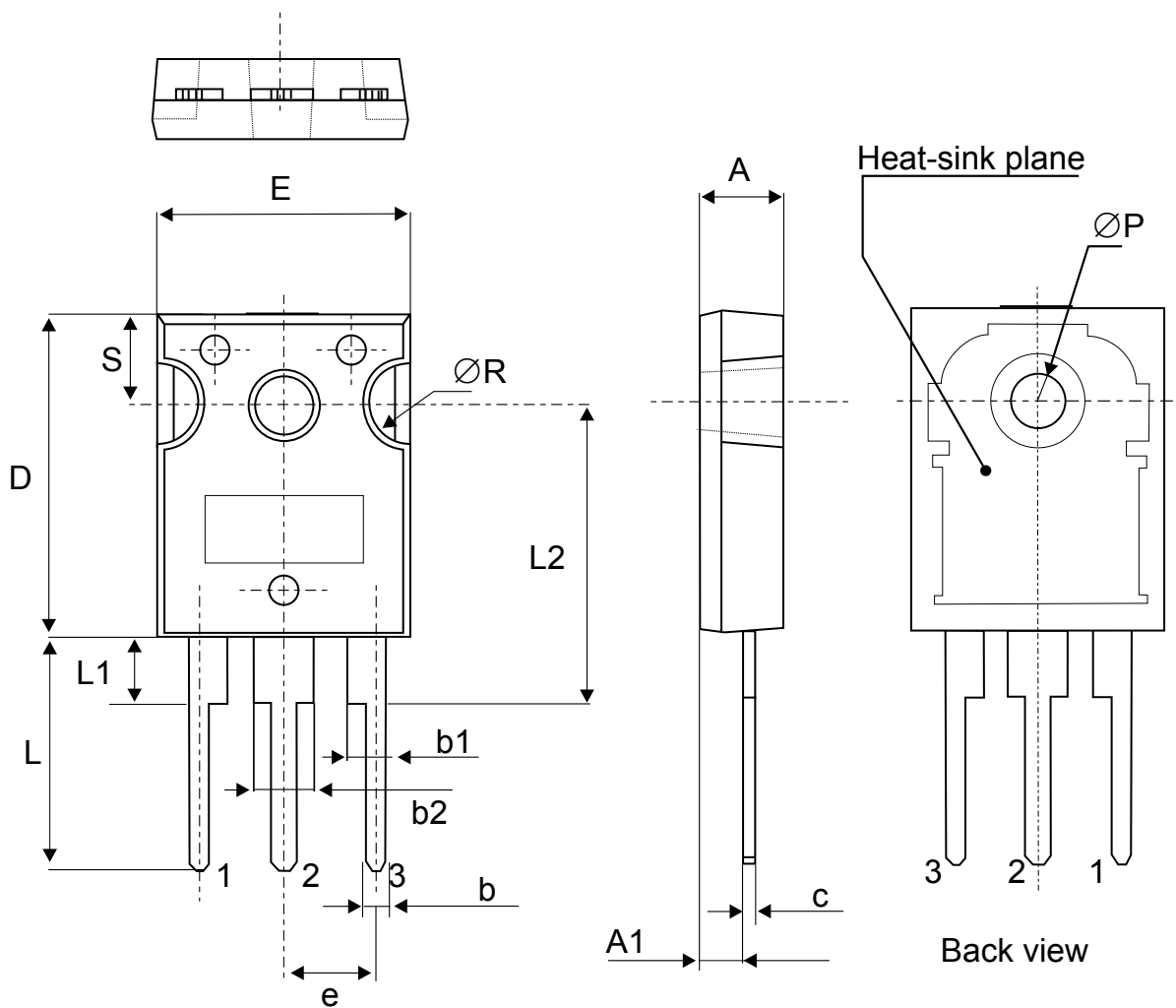
## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 2.1 TO-247 package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.8 N·m
- Maximum torque value: 1.0 N·m

Figure 8. TO-247 package outline



**Table 4. TO-247 package mechanical data**

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.15	0.191		0.203
A1	2.20		2.60	0.086		0.102
b	1.00		1.40	0.039		0.055
b1	2.00		2.40	0.078		0.094
b2	3.00		3.40	0.118		0.133
c	0.40		0.80	0.015		0.031
D	19.85		20.15	0.781		0.793
E	15.45		15.75	0.608		0.620
e	5.30	5.45	5.60	0.209	0.215	0.220
L	14.20		14.80	0.559		0.582
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
ØP	3.55		3.65	0.139		0.143
ØR	4.50		5.50	0.177		0.217
S	5.30	5.50	5.70	0.209	0.216	0.224

### 3 Ordering information

**Table 5. Order code**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS61H100CW	STPS61H100CW	TO-247	4.36 g	30	Tube

## Revision history

**Table 6. Document revision history**

Date	Revision	Changes
Oct-2003	1A	Previous version.
Sep-2006	2	Reformatted for internal distribution.
12-Mar-2012	3	Updated package dimension nomenclature and illustration in Table 5. Dimensions of actual package remain unchanged.
09-Aug-2018	4	Updated Table 1. Absolute ratings (limiting values per diode at 25 °C, unless otherwise specified) and Figure 3. Normalized avalanche power derating versus pulse duration ( $T_j = 125\text{ °C}$ ).



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